

Description:

Multilayer Chip Varistor is a family of Transient Voltage Surge Suppression products. Today, electronic circuits are becoming smaller and more sensitive to external interference. Multilayer Chip Varistor is designed to protect components from destruction of transients and ESD(Electronic Static Discharge). The wide operating voltage and energy rage make Multilayer Chip Varistor suitable for numerous applications on I/O protection , Vcc protection , Keyboard protection , LCD protection , Sensor protection etc. The Chip Varistor is manufactured by Multilayer fabrication technology providing excellent voltage clamping ability and is supplied in lead less , surface mount form , compatible with modern reflow and wave soldering procedures.

Features:

- Multilayer fabrication technology
- -55°C to +125°C operating temperature Range
- Operating voltage range VM(DC) at 5.5V to 18V
- Able to withstand ESD test of IEC-61000-4-2
- Bi-directional clamping characteristic

Applications:

Protection of cellular phones, PDA, High Speed Data Line etc.

ESD Protection for components sensitive to IEC 61000-4-2, provides circuit board transient voltage protection for transistors. Protection of Video & Audio Ports.

Device Rating And Specifications:

	Maximum Ratings						Specifications		
	Max. Continuous Working		Max. Non-Repetitive	Max. Non- Repetitive	Max. Claiming Voltage at	Nominal Voltage		Typical Capacitance	
Part Number	Vor	tage	(8/20µs)	Surge Energy (10/1000µs)	Specified At 1mA (DC) Current Current (8/20µs)		rent	@1KHz	
	V _{M(DC)}	V _{M(AC)}	I _{TM}	W _{TM}	Vc	V _{N(DC)} Min.	V _{N(DC)} Max.	С	
	(V)	(V)	(A)	(J)	(V)	(V)	(V)	(pF)	
MCVZ0402M050AGT	5.5	4	20	0.05	20 at 1A	8.0	11.0	295	
MCVZ0402M090AGT	9	6	20	0.05	23 at 1A	10.2	13.8	190	
MCVZ0402M110AGT	11	8	20	0.05	25 at 1A	12.75	17.25	160	
MCVZ0402M140AGT	14	11	20	0.05	30 at 1A	15.3	20.7	135	
MCVZ0402M180AGT	18	14	20	0.05	40 at 1A	21.6	26.4	93	

The capacitance value and energy only for reference. It is not formal specification.

Standard Testing Condition

Unless otherwise specifiedTemperature: +15°C to 35°CHumidity: 25%RH to 85%RHAtmospheric pressure: 86kPa to 106kPa



Symbol

L

W

Т

Ts

MCVZ0402 Series

1 ±0.1mm

0.5 ± 0.1mm

0.6mm (max.)

0.25 ±0.15mm

Dimensions:



Terminal electrode : Ni / Sn electrode

Specifications:

Electrical Reliability

Test Item	Tes	Specification		
High temperature storage	+125±3°C for 1,000 ho Measurement to be ma	ΔV at 1mA < 10%		
Low temperature storage	-40±3°C for 1,000 hour Measurement to be ma	ΔV at 1mA < 10%		
Humidity storage	40±2°C , 90 to 95%RH Measurement to be ma	ΔV at 1mA < 10%		
	Times : 5 cycles			
	Step	Temp.(°C)	Time(min.)	
	1	-55±3	30±3	
Temperature cycles	2	Room temp.	2~3	∆V at 1mA < 10%
	3	+125 ±3°C	30±2	
	4	Room temp.	2~3	
	Measurement to be n			

Mechanical Reliability

Test Item	Test condition / Test method	Specification
Solderability	Solder temp. : 230±5°C Immersion time : 2±0.5 sec Immersion and emersion rates : 25mm/s	Min 90% electrode shall be covered with solder.
Resistance to Soldering Heat	Pre-heating : 120°C to 150°C, 60sec Solder temp. : 260 ±5°C Immersion time : 10 ±1sec Measurement to be made after keeping at room temp. for 24 ±2h	ΔV at 1mA < 10% Disappearance of electrode due to immersion into solder shall not exceed 25% of edges of each electrode.



Mechanical Reliability

Test Item	Test condition / Test method	Specification
	Solder chip on PCB and applied 0805/1206 Series: 10N(1Kgf) for 10 sec 0402/0603 Series: 5N(0.5Kgf) for 10 sec	
Adhesive Strength of Termination	Chip varistor	No visible damage
Vibration	Solder chip on PCB. Frequency : 10Hz ~ 55Hz ~ 10 Hz (1min) Oscillation amplitude : 1.5mm Times : 2hrs in each of three perpendicular direction	No visible damage
Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of 1mm per second until the deflection becomes 1mm and then the pressure shall be maintained for 5 sec.	No visible damage ΔV at 1mA < 10%

Soldering Condition:

Typical examples of soldering processes that provide reliable joints without any damage are given in figure below:



Infrared soldering profile



Packaging:

Paper Tape specifications and Packaging quantity



Series	А	В	E	F	ØD
MCVZ0402 Series	1.12 ±0.03	0.62 ±0.03	1.75 ±0.05	3.5 ±0.05	1.55 ±0.05

Series	P0	P1	Т	W	Quantity/Reel
MCVZ0402 Series	4 ±0.1	2 ±0.1	0.6 ±0.03	8 ±0.2	10Kpcs

Tape Material : Paper tape

Dimensions : Millimetres

Reel Dimensions:



Index	Α	В	С
Dimension (mm)	178	60	13.5

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